



SINGLE N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
	18mΩ @ V _{GS} = 10V	9.0A
30V	30mΩ @ V _{GS} = 4.5V	7.0A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance (R_{DS(on)}) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

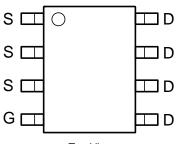
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

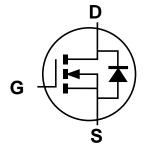
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Weight: 0.074 grams (Approximate)







Top View Internal Schematic



Equivalent circuit

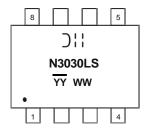
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3030LSS-13	SO-8	2500/Tape & Reel

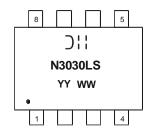
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3.Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, see http://www.diodes.com/products/packages.html.

Marking Information



Chengdu A/T Site



Shanghai A/T Site

);; = Manufacturer's Marking
N3030LS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 13 = 2013)
WW = Week (01 - 53)

YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)

May 2018

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Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage		V _{DSS}	30	V	
Gate-Source Voltage		V _{GSS}	±25	V	
Drain Current (Note 6)	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I _D	9.0 6.75	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	40	А	

Thermal Characteristics

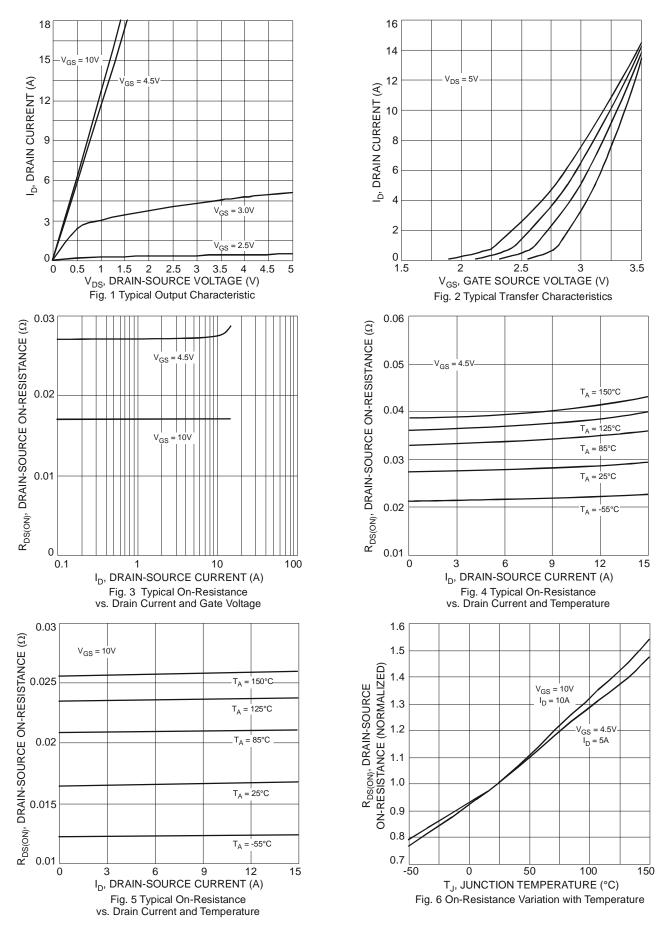
Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	1.7	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{OJA}	73	°C/W
Total Power Dissipation (Note 6)	P _D	2.5	W
Thermal Resistance, Junction to Ambient (Note 6)	R _{ÐJA}	50	°C/W
Operating and Storage Temperature Range	$T_{J_1}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 30V$, $V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)		_	_	±1	μΑ	$V_{GS} = \pm 25V$, $V_{DS} = 0V$
Gate Threshold Voltage	V _{GS(th)}	1	_	2.1	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance	R _{DS (ON)}	_	15.7 26.4	18 30	mΩ	$V_{GS} = 10V, I_D = 9A$ $V_{GS} = 4.5V, I_D = 7A$
Forward Transconductance	g fs	_	5.8	_	S	$V_{DS} = 10V, I_{D} = 9A$
Diode Forward Voltage	V _{SD}	0.5	0.7	1.2	V	V _{GS} = 0V, I _S = 2.1A
DYNAMIC CHARACTERISTICS (Note 8)			•	•	•	
Input Capacitance	C _{iss}	_	741	_	pF	V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	Coss	_	124	_	pF	
Reverse Transfer Capacitance	C _{rss}	_	95	_	pF	
Gate Resistance	R_{G}	0.30	0.88	2.5	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
SWITCHING CHARACTERISTICS (Note 8)						
Total Gate Charge	0	_	7.6	12		$V_{DS} = 15V, V_{GS} = 4.5V, I_{D} = 9A$
Total Gate Charge	Q_g	_	16.7	25	nC	
Gate-Source Charge	Q_{gs}	_	1.9	_	IIC	$V_{DS} = 15V$, $V_{GS} = 10V$, $I_{D} = 9A$
Gate-Drain Charge	Q_{gd}	_	5.2	_		
Turn-On Delay Time	t _{d(on)}	_	4.0	_		$V_{GS} = 10V, V_{DS} = 15V,$ $R_L = 15\Omega, R_G = 6\Omega$
Rise Time	t _r	_	4.4	_		
Turn-Off Delay Time	t _{d(off)}		23.0	_	ns	
Fall Time	t _f	_	9.4	_		

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing. Notes:







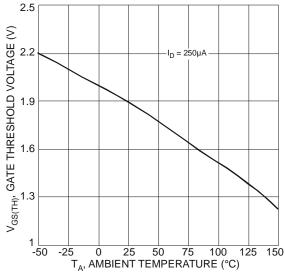
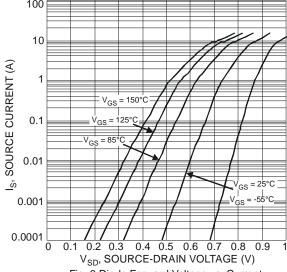
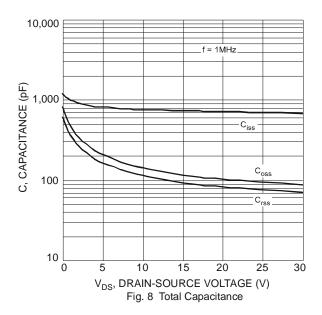


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







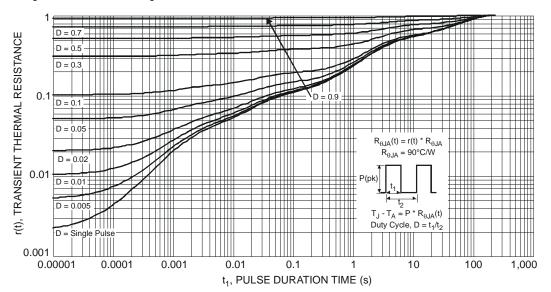
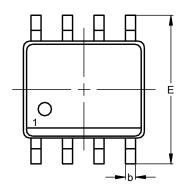


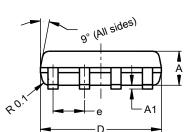
Fig. 10 Transient Thermal Response

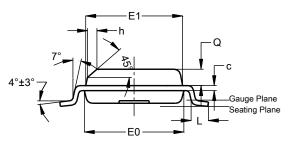


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.







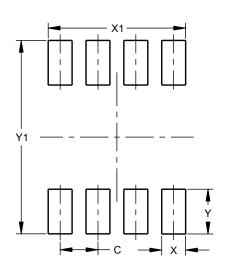
SO-8

SO-8

SO-8					
Dim	Min	Max	Тур		
Α	1.40	1.50	1.45		
A1	0.10	0.20	0.15		
p	0.30	0.50	0.40		
O	0.15	0.25	0.20		
D	4.85	4.95	4.90		
Е	5.90	6.10	6.00		
E1	3.80	3.90	3.85		
E0	3.85	3.95	3.90		
е			1.27		
h	-		0.35		
Г	0.62	0.82	0.72		
Ø	0.60	0.70	0.65		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)		
С	1.27		
Х	0.802		
X1	4.612		
Υ	1.505		
Y1	6.50		



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